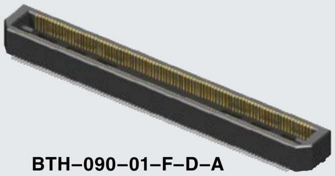
F-218 (Rev 10OCT17)

samtec

10 YEAR MFG WITH 50 µ" GOLD
EXTENDED LIFE PRODUCT
HIGH MATING CYCLES


BTH–090–01–F–D–A


BTH–030–01–L–D–RA–WT

(0.50 mm) .0197"

BTH SERIES

BASIC BLADE & BEAM HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTH

Insulator Material:
Black LCP
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating:
2.0 A per pin
(2 pins powered)
Flammability Rating:
UL 94 VO
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating: 275 VAC
Max Cycles: 100
RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
Vertical=
(0.10 mm) .004" max (030-090)
Vertical=
(0.15 mm) .006" max (120-150)*
Right-angle=
(0.15 mm) .006" max (030-090)*
*(.004" stencil solution
may be available; contact
IPG@samtec.com)
Board Stacking:
For applications requiring more than two connectors per board or 90 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

ALSO AVAILABLE
(MOQ Required)

- 30 µ" (0.76 µm) Gold
- Edge Mount Capability
- 8 mm, 11 mm, 16 mm, 19 mm and 22 mm Stack Height (Caution: Some automatic placement/ inspection machines may have component height restrictions. Please consult machinery specifications.) (11 mm, 16 mm, 19 mm and 22 mm not available with 50 positions)

Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

BTH – NO. OF POSITIONS PER ROW – 01 – PLATING OPTION – D – A – OTHER OPTION

Mates with:
BSH

NO. OF POSITIONS PER ROW
–030, –050, –060,
–090, –120, –150

PLATING OPTION

–F
= Gold Flash on contact,
Matte Tin on tail

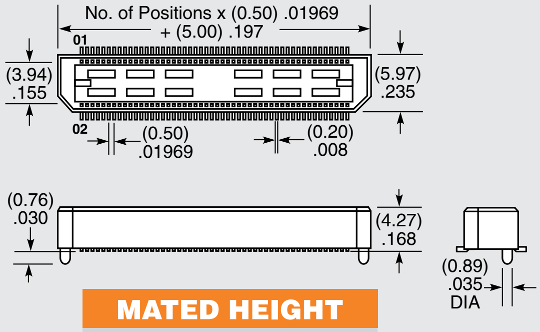
–L
= 10 µ" (0.25 µm)
Gold on contact,
Matte Tin on tail

–C*
= Electro-Polished Selective
50 µ" (1.27 µm) min Au
over 150 µ" (3.81 µm) Ni on
Signal Pins in contact area,
Matte Tin over
50 µ" (1.27 µm) min Ni
on all solder tails

OTHER OPTION

–K
= (7.00 mm) .276" DIA
Polyimide Film Pick
& Place Pad

–TR
= Tape & Reel
(120 positions maximum)



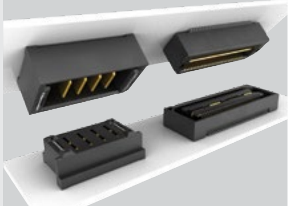
***Note:** –C Plating passes
10 year MFG testing

MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
–01	(5.00) .197

*Processing conditions will affect mated height.

POWER/SIGNAL APPLICATION


Compatible with
UMPT/UMPS for flexible
two-piece power/signal solutions

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